



Final Product Change Notification

202003011F01

Issue Date: 29-Mar-2020
Effective Date: 27-Jun-2020

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QUALITY

Management Summary

The LPC176x will be upgraded to revision C and Powerchip will be added as a second source wafer fab for product in LQFP100 package.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Location	<input checked="" type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Process	<input type="checkbox"/> Errata
<input checked="" type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

LPC176x Revision Change to Rev C and Addition of 2nd Source Wafer Fab for Product in LQFP100 Package

Description of Change

The silicon wafers are currently produced in SSMC. Powerchip (PTCF12) has been qualified as a 2nd source wafer fab for LPC176x products in the LQFP100 packages.

- No change in data sheet
- No change in ordering part number / 12NC
- Final test location remains unchanged at NXP Assembly and Test Kaohsiung (ATKH)

The die revision will be changed from Rev A to Rev C which includes design changes to fix the following errata: ADC.1, GPIO.2, I2S.1, PLL0.1 and USB.1.

An updated errata sheet is available: https://www.nxp.com/docs/en/errata/ES_LPC176X.pdf.

The mold compound will be changed to CEL-9240HF10AN for assembly of Powerchip die.

Reason for Change

To ensure wafer supply with increased capacity and to resolve errata issues.

Identification of Affected Products

Top side marking

The product revision located at the last character of the last line in the top side marking will change to "C".

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 24-Jun-2020

Anticipated Impact on Form, Fit, Function, Reliability or Quality

The product marking changes and errata issues are resolved as identified above.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 28-Apr-2020.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Tim Camenzind

Position Quality Manager

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NXP Quality Management Team.

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
LPC1766FBD100K	935287917557	LPC1766FBD100	32-bit ARM M3	SOT407-1	LQFP100	RFS	MCUs
LPC1766FBD100,551	935287917551	LPC1766FBD100	32-bit ARM M3	SOT407-1	LQFP100	RFS	MCUs
LPC1768FBD100,551	935288608551	LPC1768FBD100	32-bit ARM M3	SOT407-1	LQFP100	RFS	MCUs
LPC1767FBD100,551	935289808551	LPC1767FBD100	32-bit ARM M3	SOT407-1	LQFP100	RFS	MCUs
LPC1767FBD100K	935289808557	LPC1767FBD100	32-bit ARM M3	SOT407-1	LQFP100	RFS	MCUs
LPC1768FBD100K	935288608557	LPC1768FBD100	32-bit ARM M3	SOT407-1	LQFP100	RFS	MCUs
LPC1765FBD100K	935287918557	LPC1765FBD100	32-bit ARM M3	SOT407-1	LQFP100	RFS	MCUs
LPC1764FBD100,551	935287919551	LPC1764FBD100	32-bit ARM M3	SOT407-1	LQFP100	RFS	MCUs
LPC1769FBD100,551	935290522551	LPC1769FBD100	32-bit ARM M3	SOT407-1	LQFP100	RFS	MCUs
LPC1763FBD100,551	935291276551	LPC1763FBD100	32-bit ARM M3	SOT407-1	LQFP100	RFS	MCUs
LPC1764FBD100K	935287919557	LPC1764FBD100	32-bit ARM M3	SOT407-1	LQFP100	RFS	MCUs